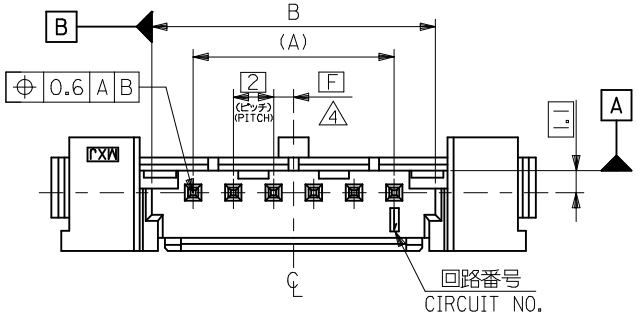
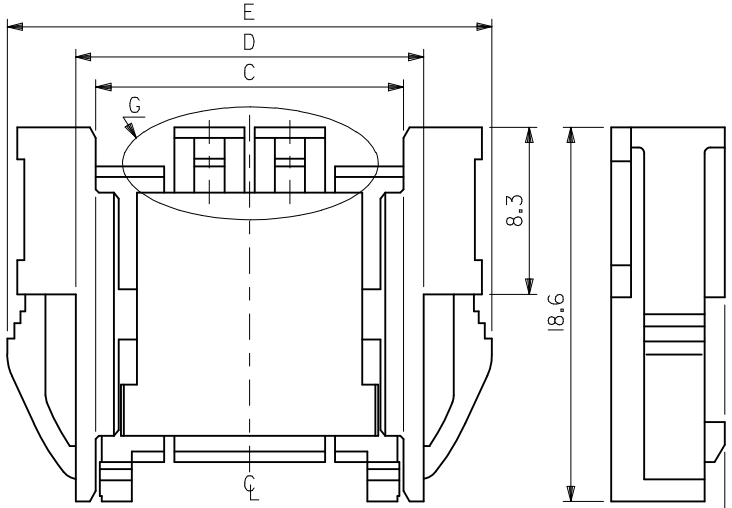
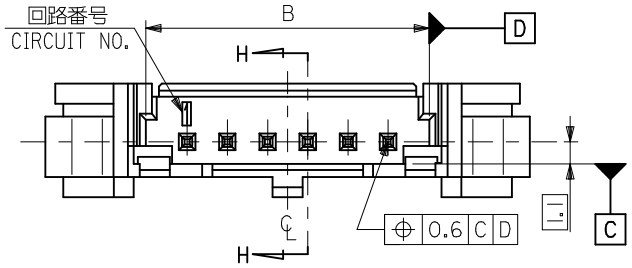
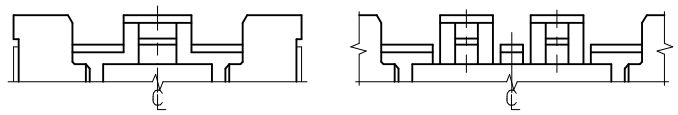
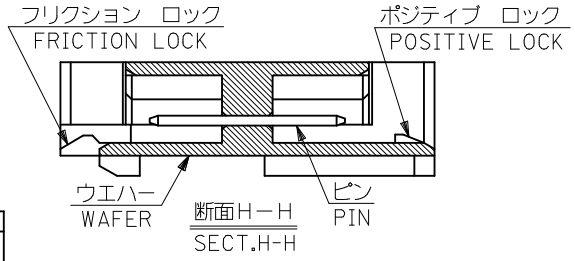


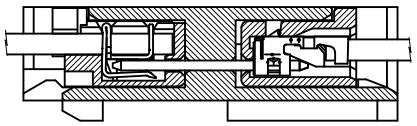




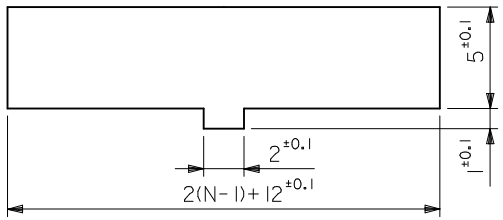


DETAIL G





嵌合状態図
CROSS-SECTION OF MATED CONNECTORS



参考パネルスロット寸法
PANEL SLOT DIM.(REF.)
(パネル厚：0．8～2．0)
(THICKNESS ：0.8-2.0)

無 鉛
LEAD FREE

注 記
NOTES

1. 材料 MATERIAL
   ウエハー：PBT,UL94V-0
   WAFER ：PBT,UL94V-0
   ピン ：黄銅、スズメッキ(□0.5)
   PIN ：BRASS,TIN PLATED (0.5 SQUARE)
2. 適合圧着ハウジング ：51090-**00
   MATING CRIMP RECEPTACLE HOUSING:51090-**00
3. 適合圧接ハウジング ：52484-**1*
   MATING IDT RECEPTACLE HOUSING:52484-**1*
4. B寸法の℄から、隣接するピンの℄までの位置を示す。
   THIS DIMENSION SHOWS SPACING BETWEEN CENTER OF PIN AND CENTER OF B DIMENSION.
5. 本図は、6極を示す。
   6 CIRCUIT VERSION IS SHOWN IN THIS DRAWING.
6. ハウジングは、パネル打抜き側から挿入すること。
   INSERT HOUSING FROM PUNCH SIDE OF PANEL.
7. 色 COLOR
   53358-**40：自然色 (WHITE)
   53358-**42：赤色 (RED)
   53358-**43：黄色 (YELLOW)
   53358-**44：青色 (BLUE)

F	E	D	C	B	A	ENG. NO.	CKT.
1	16.1	9.3	7.3	6.1	2	53358-024*	2
2	18.1	11.3	9.3	8.1	4	-034*	3
1	20.1	13.3	11.3	10.1	6	-044*	4
2	22.1	15.3	13.3	12.1	8	-054*	5
1	24.1	17.3	15.3	14.1	10	-064*	6
2	26.1	19.3	17.3	16.1	12	-074*	7
1	28.1	21.3	19.3	18.1	14	-084*	8
2	30.1	23.3	21.3	20.1	16	-094*	9
1	32.1	25.3	23.3	22.1	18	-104*	10
2	34.1	27.3	25.3	24.1	20	-114*	11
1	36.1	29.3	27.3	26.1	22	-124*	12
2	38.1	31.3	29.3	28.1	24	-134*	13
1	40.1	33.3	31.3	30.1	26	-144*	14
2	42.1	35.3	33.3	32.1	28	53358-154*	15

REVISED
EC NO: J2015-0419
DRWN:KMATSUYAMA 2014/09/26
CH'KD:KASAKAWA 2014/09/29
APPR:NUKITA 2014/11/11
DESCRIPTION
REV
B

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY	SSHIBATA
DATE	2012/11/21
CHECKED BY	JMIYAZAWA
DATE	2012/11/21
APPROVED BY	YOITO
DATE	2012/11/21
MATERIAL NO.	SEE CHART
DOCUMENT NO.	SD-53358-001
SHEET NO.	1 OF 1

TITLE: 2.0 WIRE TO WIRE CONN. PANEL MOUNT WAFER ASSY

molex

SIZE A3

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